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REMARKS

In response to the action, Applicants have amended claims 1 and 6 and cancelled claims 5 and 10. Applicants respectfully request reconsideration in view of the amendments and the following remarks.

Applicants amended claims 1 and 6 to include removing copper for further distinction in view of the cited art. The specification at paragraph 9, lines 1 and 2, provides a basis for the limitation. Applicants respectfully submit that these amendments enter no new matter.

The action rejects claim 5 under 35 U.S.C. § 112, second paragraph, as being a dependent claim inconsistent with its independent claim. In response to the rejection, Applicants have cancelled claim 5 to render the rejection moot.

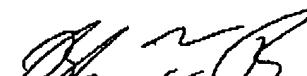
The action rejects claims 1 to 4 as being unpatentable over Small (US Pat. No. 5,981,454) in view of Chopra (US Pat. No. 6,276,996) or Verhaverbeke (US Pat. No. 5,972,123). Small discloses a post-polishing treatment solution that can be useful in a two-step polishing process—Col. 6, lines 4 to 6. In this process, the solution facilitates oxidizing the metal surface and “the subsequent abrasion of the oxide surface with an emulsion slurry”. Claim 1 includes a polishing solution useful for polishing and removing copper without abrasives. Unlike Applicants’ abrasive-free claim 1, Small relies upon an emulsion slurry to remove copper. Thus, since the combined references fail to disclose an abrasive-free slurry for polishing and removing copper, Applicants respectfully submit that the combined references fail to disclose or suggest claims 1 to 4, as amended.

Applicants respectfully submit that the application is in proper form for allowance. If a telephone call would expedite prosecution, please call Applicants' attorney at (302) 283-2136.

Respectfully submitted,

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Date



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